



BSI Standards Publication

Semiconductor devices — Mechanical and climatic test methods

Part 10: Mechanical shock — device and subassembly

National foreword

This British Standard is the UK implementation of EN IEC 60749-10:2022. It is identical to IEC 60749-10:2022. It supersedes BS EN 60749-10:2002, which will be withdrawn on 2 January 2023.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

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Dispositif et sous-ensemble
(IEC 60749-10:2022)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 10: Mechanischer Schock -
Bauelemente und Unterbaugruppe
(IEC 60749-10:2022)

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European foreword

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